# 2SA0900 (2SA900)

## Silicon PNP epitaxial planar type

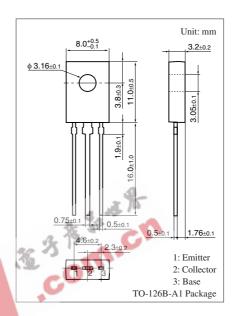
For low-frequency Power amplification Complementary to 2SC1868

#### ■ Features

- ullet Low collector-emitter saturation voltage  $V_{CE(sat)}$
- TO-126B package which requires no insulation plate for installation to the heat sink

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	-20	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	-18	V	
Emitter-base voltage (Collector open)	$V_{EBO}$	-5	V	
Collector current	$I_C$	-1	A	
Peak collector current	$I_{CP}$	-2	A	
Collector power dissipation	P <sub>C</sub>	1.2	W	
Junction temperature	T <sub>j</sub>	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	



### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

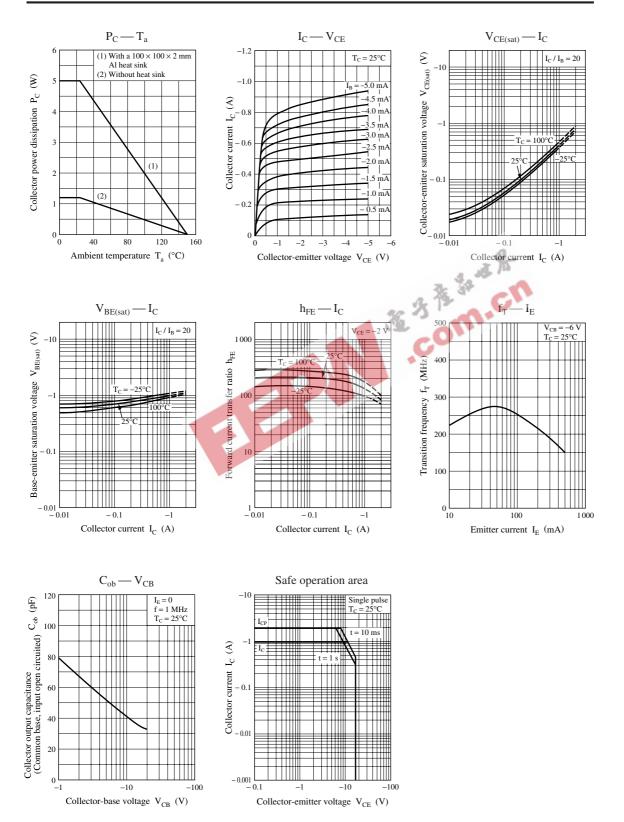
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_{\rm C} = -10 \; \mu \text{A}, \; I_{\rm E} = 0$	-20			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_{\rm C} = -1 \text{ mA}, I_{\rm B} = 0$	-18			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = -10 \mu A, I_C = 0$	-5			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = -10 \text{ V}, I_E = 0$			-1	μΑ
Collector-emitter cutoff current (Base open)	$I_{CEO}$	$V_{CE} = -18 \text{ V}, I_B = 0$			-10	μΑ
Forward current transfer ratio	h <sub>FE1</sub> *	$V_{CE} = -2 \text{ V}, I_{C} = -500 \text{ mA}$	130		280	_
	h <sub>FE2</sub>	$V_{CE} = -2 \text{ V}, I_{C} = -1.5 \text{ A}$	50			
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = -1 \text{ A}, I_B = -50 \text{ mA}$			- 0.5	V
Base-emitter saturation voltage	V <sub>BE(sat)</sub>	$I_C = -500 \text{ mA}, I_B = -50 \text{ mA}$			-1.2	V
Transition frequency	$f_T$	$V_{CB} = -6 \text{ V}, I_E = 50 \text{ mA}, f = 200 \text{ MHz}$		200		MHz
Collector output capacitance (Common base, input open circuited)	C <sub>ob</sub>	$V_{CB} = -6 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		40		pF

 $Note) \ 1. \ Measuring \ methods \ are \ based \ on \ JAPANESE \ INDUSTRIAL \ STANDARD \ JIS \ C \ 7030 \ measuring \ methods \ for \ transistors.$ 

#### 2. \*: Rank classification

Rank	R	S
$h_{FE1}$	130 to 210	180 to 280

Note) The part numbers in the parenthesis show conventional part number.



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